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Listing of Claims:

Please amend claims 50, 54 and 56, add new claims 58-61 as provided herewith, and cancel claims 46, 47, 49, 52 and 53 without prejudice. This listing of claims will replace all prior versions, and listings, of claims in this application:

Claims 1-47 (Cancelled).

48. (Previously presented) A maleimide composition comprising a maleimide-containing curable component which when dispensed between a 300 x 300 mil silica die and a Ag coated lead frame as a 1 mil bondline and cured for 1 minute at a temperature of about 200°C, demonstrates an initial adhesion value of at least 115 lbs and a post pressure cooker adhesion of at least 83 lbs.

Claim 49 (Cancelled).

- 50. (Currently amended) The composition of Claim 49 48, substantially free of inert diluent.
 - 51. (Previously presented) A composition comprising
 - (a) a liquid maleimide comprising:

$$x = \begin{bmatrix} 0 \\ N \\ 0 \end{bmatrix}_{m} \tag{I}$$

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wherein:

each R is independently hydrogen or lower alkyl,

-X is a branched chain alkyl or alkylene species having at least 12 carbon atoms, and

m is 1, 2 or 3; and

(b) a peroxide cure initiator.

Claims 52-53 (Cancelled).

- 54. (Currently amended) An assembly comprising a first article permanently adhered to a second article by a cured aliquot of the composition of Claim 49 48.
- 55. (Previously presented) An assembly comprising a first article permanently adhered to a second article by a cured aliquot of the composition of Claim 51.
 - 56. (Currently amended) The composition of Claim 49 48, further comprising a filler.
 - 57. (Previously presented) The composition of Claim 51, further comprising a filler.
- 58. (New) The composition of claim 48, wherein the maleimide-containing curable component is a liquid.
 - 59. (New) The composition of Claim 51, substantially free of inert diluent.
 - 60. (New) The composition of Claim 54 wherein the first article is a silicon die.
 - 61. (New) The composition of Claim 55 wherein the first article is a silicon die.